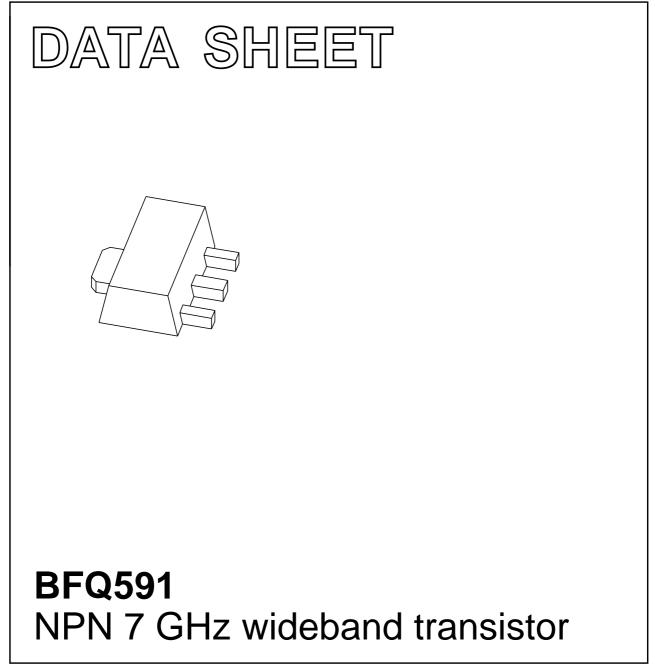
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2002 Jan 07 2002 Feb 04



HILIP

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

Intended for applications in the GHz range such as MATV or CATV amplifiers and RF communications subscribers equipment.

DESCRIPTION

NPN wideband transistor in a SOT89 plastic package.

MARKING

TYPE NUMBER	MARKING CODE
BFQ591	ВСр

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-	20	V
V _{CEO}	collector-emitter voltage	open base	-	-	15	V
I _C	collector current (DC)		-	-	200	mA
P _{tot}	total power dissipation	$T_s \le 90 \ ^{\circ}C$; note 1	-	-	2.25	W
h _{FE}	DC current gain	I _C = 70 mA; V _{CE} = 8 V	60	90	250	
C _{re}	feedback capacitance	I _C = 0; V _{CB} = 12 V; f = 1 MHz	-	0.8	-	pF
f _T	transition frequency	I_{C} = 70 mA; V_{CE} = 12 V; f = 1 GHz	-	7	-	GHz
G _{UM}	maximum unilateral power gain	I _C = 70 mA; V _{CE} = 12 V; f = 900 MHz; T _{amb} = 25 °C	-	11	-	dB
s ₂₁ ²	insertion power gain	I_{C} = 70 mA; V_{CE} = 12 V; f = 900 MHz; T_{amb} = 25 °C	-	10	-	dB

Note

1. T_s is the temperature at the soldering point of the collector pin.

Product specification

PINNING

PIN	DESCRIPTION	
1	emitter	
2	collector	
3	base	

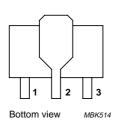


Fig.1 Simplified outline (SOT89).

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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	20	V
V _{CEO}	collector-emitter voltage	open base	-	15	V
V _{EBO}	emitter-base voltage	open collector	-	3	V
I _C	collector current (DC)		-	200	mA
P _{tot}	total power dissipation	$T_s \le 90 \ ^{\circ}C$; note 1	-	2.25	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	$T_s \le 90 \ ^{\circ}C$; note 1	38	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

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CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$; unless otherwise specified.

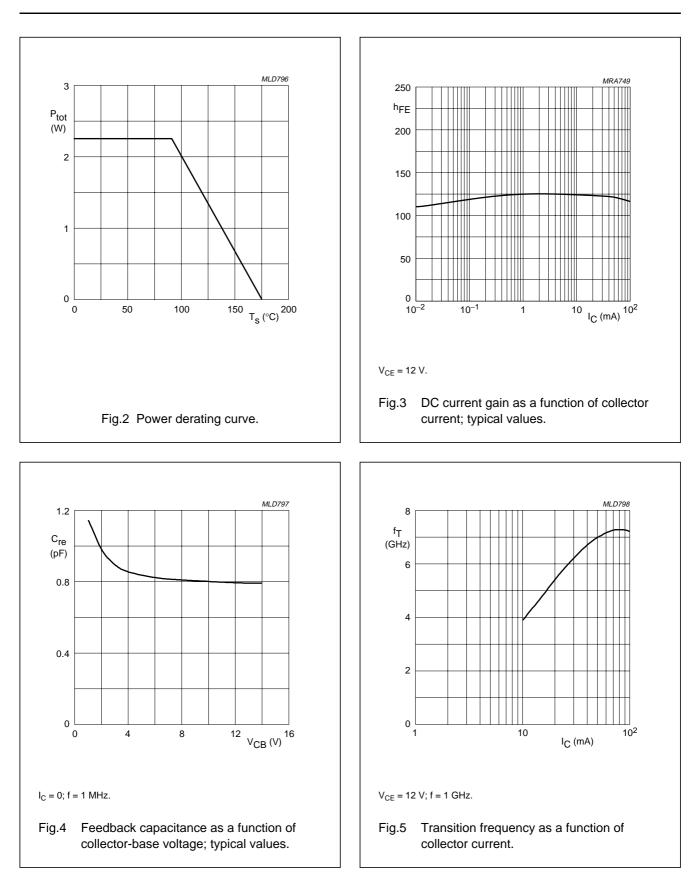
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)CBO}	collector-base breakdown voltage	$I_{\rm C} = 0.1 \text{ mA}; I_{\rm E} = 0$	-	-	20	V
V _{(BR)CES}	collector-emitter breakdown voltage	I _C = 0.1 mA; I _B = 0	-	-	15	V
V _{(BR)EBO}	emitter-base breakdown voltage	$I_{E} = 0.1 \text{ mA}; I_{C} = 0$	_	_	3	V
I _{CBO}	collector-base leakage current	$I_{E} = 0; V_{CB} = 10$	-	-	100	nA
h _{FE}	DC current gain	I _C = 70 mA ; V _{CE} = 8 V	60	90	250	
C _{re}	feedback capacitance	I _C = 0; V _{CB} = 12 V; f = 1 MHz	-	0.8	-	pF
f _T	transition frequency	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz	-	7	-	GHz
G _{UM}	maximum unilateral power gain; note 1	I_C = 70 mA; V_{CE} = 12 V; T_{amb} = 25 °C				
		f = 900 MHz	-	11	-	dB
		f = 2 GHz	-	5.5	-	dB
s ₂₁ ²	insertion power gain	I _C = 70 mA; V _{CE} = 12 V; f = 1 GHz; T _{amb} = 25 °C	-	10	-	dB
Vo	output voltage	note 2	-	700	-	mV

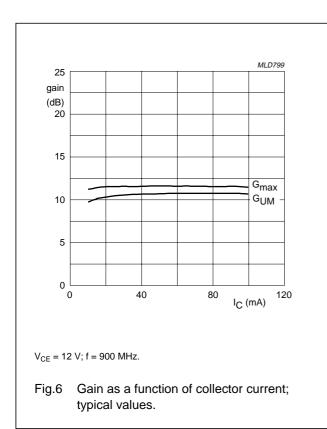
Notes

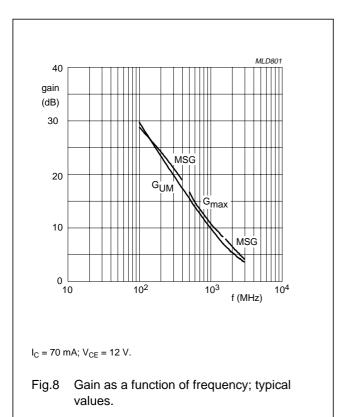
- 1. G_{UM} is the maximum unilateral power gain, assuming s_{12} is zero and $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1-|s_{11}|^2)(1-|s_{22}|^2)} dB$.
- 2. $d_{im} = 60 \text{ dB}$ (DIN45004B); $V_p = V_o$; $V_q = V_o 6 \text{ dB}$; $f_p = 795.25 \text{ MHz}$; $f_q = 803.25 \text{ MHz}$; $f_r = 803.25 \text{ MHz}$; measured at $f_{(p+q+r)} = 793.25 \text{ MHz}$.

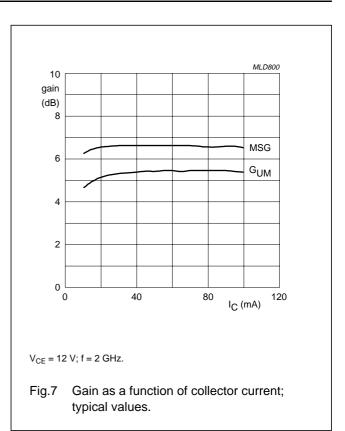
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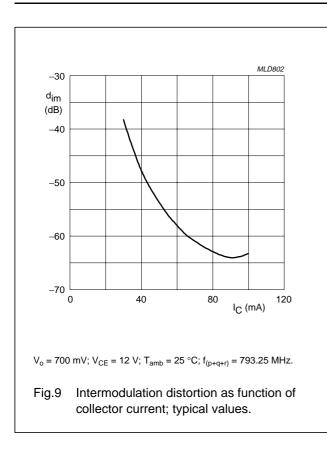
NPN 7 GHz wideband transistor

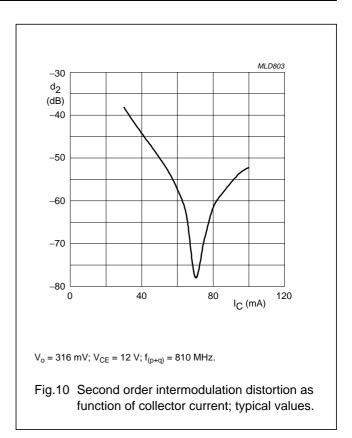












SPICE parameters for the BFQ591 die.

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	1.341	fA
2	BF	123.5	_
3	NF	.988	_
4	VAF	75.85	V
5	IKF	9.656	mA
6	ISE	232.2	fA
7	NE	2.134	_
8	BR	10.22	-
9	NR	1.016	_
10	VAR	1.992	V
11	IKR	294.1	mA
12	ISC	211.0	aA
13	NC	997.2	-
14	RB	5.00	Ω
15	IRB	1.000	μA
16	RBM	5.00	Ω
17	RE	1.275	Ω
18	RC	920.6	Ω
19 ⁽¹⁾	ХТВ	0.000	_
20 ⁽¹⁾	EG	1.110	eV
21(1)	XTI	3.000	_
22	CJE	3.821	pF
23	VJE	600.0	mV
24	MJE	348.5	_
25	TF	13.60	ps
26	XTF	71.73	-
27	VTF	10.28	V
28	ITF	1.929	mA
29	PTF	0.000	deg
30	CJC	1.409	fF
31	VJC	219.4	mV
32	MJC	166.5	-
33	XCJ	2.340	-
34	TR	543.7	ps
35 ⁽¹⁾	CJS	0.000	F
36 ⁽¹⁾	VJS	750.0	mV
37 ⁽¹⁾	MJS	0.000	-
38	FC	733.2	_

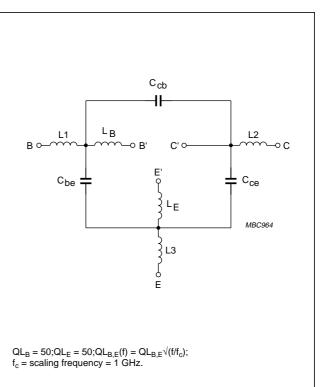


Fig.11 Package equivalent circuit SOT89.

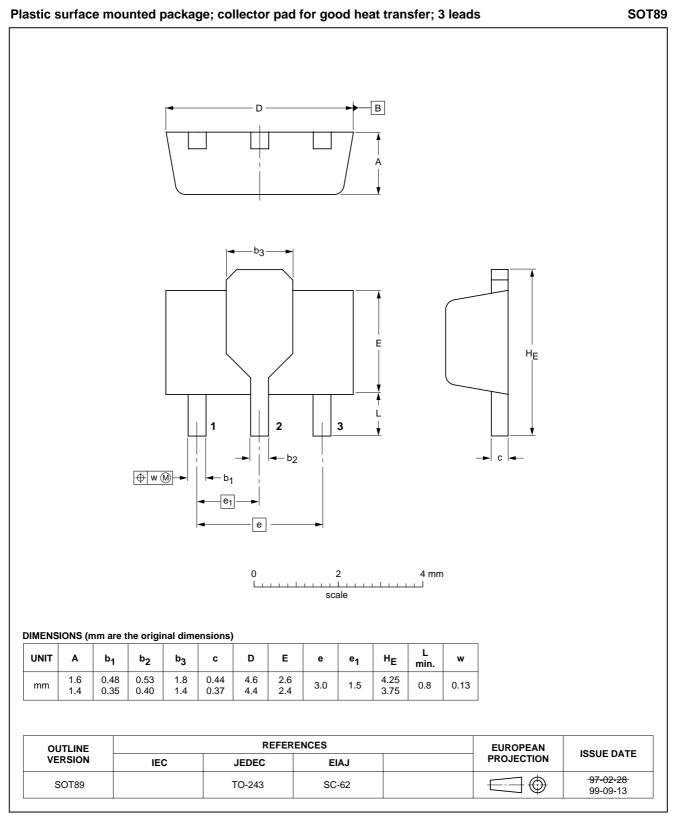
List of components (see Fig.11)

DESIGNATION	VALUE	UNIT
C _{be}	16	fF
C _{cb}	150	fF
C _{ce}	150	fF
L1	1	nH
L2	0.01	nH
L3	1	nH
L _B	1.2	nH
LE	1.2	nH

Note

1. These parameters have not been extracted, the default values are shown.

PACKAGE OUTLINE



BFQ591

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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Printed in The Netherlands

613516/03/pp12

Date of release: 2002 Feb 04

Document order number: 9397 750 09271

SCA74

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